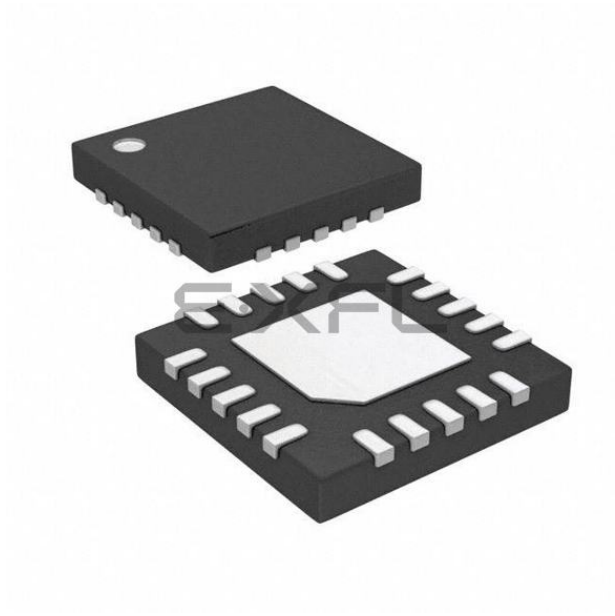


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	LINbus, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	12
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 5.5V
Data Converters	A/D 12x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-UFQFN Exposed Pad
Supplier Device Package	20-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1578-i-gz

TABLE 3-15: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 27 (Continued)											
DABh	PWM2CON	EN	—	OUT	POL	MODE<1:0>		—	—	0-00 00--	0-00 00--
DACh	PWM2INTE	—	—	—	—	OFIE	PHIE	DCIE	PRIE	---- 000	---- 000
DADh	PWM2INTF	—	—	—	—	OFIF	PHIF	DCIF	PRIF	---- 000	---- 000
DAEh	PWM2CLKCON	—	PS<2:0>			—	—	CS<1:0>		-000 -000	-000 --00
DAFh	PWM2LDCON	LDA	LDT	—	—	—	—	LDS<1:0>		00-- -000	00-- --00
DB0h	PWM2OFCON	—	OFM<1:0>		OFO	—	—	OFS<1:0>		-000 -000	-000 --00
DB1h	PWM3PHL	PH<7:0>								xxxx xxxx	uuuu uuuu
DB2h	PWM3PHH	PH<15:8>								xxxx xxxx	uuuu uuuu
DB3h	PWM3DCL	DC<7:0>								xxxx xxxx	uuuu uuuu
DB4h	PWM3DCH	DC<15:8>								xxxx xxxx	uuuu uuuu
DB5h	PWM3PRL	PR<7:0>								xxxx xxxx	uuuu uuuu
DB6h	PWM3PRH	PR<15:8>								xxxx xxxx	uuuu uuuu
DB7h	PWM3OFL	OF<7:0>								xxxx xxxx	uuuu uuuu
DB8h	PWM3OFH	OF<15:8>								xxxx xxxx	uuuu uuuu
DB9h	PWM3TMRL	TMR<7:0>								xxxx xxxx	uuuu uuuu
DBAh	PWM3TMRH	TMR<15:8>								xxxx xxxx	uuuu uuuu
DBBh	PWM3CON	EN	—	OUT	POL	MODE<1:0>		—	—	0-00 00--	0-00 00--
DBCh	PWM3INTE	—	—	—	—	OFIE	PHIE	DCIE	PRIE	---- 000	---- 000
DBDh	PWM3INTF	—	—	—	—	OFIF	PHIF	DCIF	PRIF	---- 000	---- 000
DBEh	PWM3CLKCON	—	PS<2:0>			—	—	CS<1:0>		-000 -000	-000 --00
DBFh	PWM3LDCON	LDA	LDT	—	—	—	—	LDS<1:0>		00-- -000	00-- --00
DC0h	PWM3OFCON	—	OFM<1:0>		OFO	—	—	OFS<1:0>		-000 -000	-000 --00
DC1h	PWM4PHL	PH<7:0>								xxxx xxxx	uuuu uuuu
DC2h	PWM4PHH	PH<15:8>								xxxx xxxx	uuuu uuuu
DC3h	PWM4DCL	DC<7:0>								xxxx xxxx	uuuu uuuu
DC4h	PWM4DCH	DC<15:8>								xxxx xxxx	uuuu uuuu
DC5h	PWM4PRL	PR<7:0>								xxxx xxxx	uuuu uuuu
DC6h	PWM4PRH	PR<15:8>								xxxx xxxx	uuuu uuuu
DC7h	PWM4OFL	OF<7:0>								xxxx xxxx	uuuu uuuu
DC8h	PWM4OFH	OF<15:8>								xxxx xxxx	uuuu uuuu

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, r = reserved. Shaded locations are unimplemented, read as '0'.
Note 1: PIC16(L)F1578/9 only.
2: PIC16F1574/5/8/9 only.
3: Unimplemented, read as '1'.

TABLE 3-15: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 31											
F8Ch — FE3h	—	Unimplemented								—	—
FE4h	STATUS_ SHAD	—	—	—	—	—	Z_SHAD	DC_SHAD	C_SHAD	---- -xxx	---- -uuu
FE5h	WREG_ SHAD	Working Register Shadow								xxxx xxxx	uuuu uuuu
FE6h	BSR_ SHAD	—	—	—	Bank Select Register Shadow					---x xxxx	---u uuuu
FE7h	PCLATH_ SHAD	—	Program Counter Latch High Register Shadow							-xxx xxxx	uuuu uuuu
FE8h	FSR0L_ SHAD	Indirect Data Memory Address 0 Low Pointer Shadow								xxxx xxxx	uuuu uuuu
FE9h	FSR0H_ SHAD	Indirect Data Memory Address 0 High Pointer Shadow								xxxx xxxx	uuuu uuuu
FEAh	FSR1L_ SHAD	Indirect Data Memory Address 1 Low Pointer Shadow								xxxx xxxx	uuuu uuuu
FEBh	FSR1H_ SHAD	Indirect Data Memory Address 1 High Pointer Shadow								xxxx xxxx	uuuu uuuu
FECh	—	Unimplemented								—	—
FEDh	STKPTR	—	—	—	Current Stack Pointer					---1 1111	---1 1111
FEEh	TOSL	Top-of-Stack Low byte								xxxx xxxx	uuuu uuuu
FEFh	TOSH	—	Top-of-Stack High byte							-xxx xxxx	-uuu uuuu

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, r = reserved. Shaded locations are unimplemented, read as '0'.
Note 1: PIC16(L)F1578/9 only.
2: PIC16F1574/5/8/9 only.
3: Unimplemented, read as '1'.

4.3 Code Protection

Code protection allows the device to be protected from unauthorized access. Internal access to the program memory is unaffected by any code protection setting.

4.3.1 PROGRAM MEMORY PROTECTION

The entire program memory space is protected from external reads and writes by the $\overline{CP}$ bit in Configuration Words. When $\overline{CP}$ = 0, external reads and writes of program memory are inhibited and a read will return all '0's. The CPU can continue to read program memory, regardless of the protection bit settings. Writing the program memory is dependent upon the write protection setting. See **Section 4.4 "Write Protection"** for more information.

4.4 Write Protection

Write protection allows the device to be protected from unintended self-writes. Applications, such as bootloader software, can be protected while allowing other regions of the program memory to be modified.

The WRT<1:0> bits in Configuration Words define the size of the program memory block that is protected.

4.5 User ID

Four memory locations (8000h-8003h) are designated as ID locations where the user can store checksum or other code identification numbers. These locations are readable and writable during normal execution. See **Section 10.4 "User ID, Device ID and Configuration Word Access"** for more information on accessing these memory locations. For more information on checksum calculation, see the "*PIC16(L)F157x Memory Programming Specification"* (DS40001766).

4.6 Device ID and Revision ID

The 14-bit device ID word is located at 8006h and the 14-bit revision ID is located at 8005h. These locations are read-only and cannot be erased or modified. See **Section 10.4 "User ID, Device ID and Configuration Word Access"** for more information on accessing these memory locations.

Development tools, such as device programmers and debuggers, may be used to read the Device ID and Revision ID.

6.13 Power Control (PCON) Register

The Power Control (PCON) register contains flag bits to differentiate between a:

- Power-On Reset ($\overline{POR}$)
- Brown-Out Reset ($\overline{BOR}$)
- Reset Instruction Reset ($\overline{RI}$)
- $\overline{MCLR}$ Reset ($\overline{RMCLR}$)
- Watchdog Timer Reset ($\overline{RWDT}$)
- Stack Underflow Reset (STKUNF)
- Stack Overflow Reset (STKOVF)

The PCON register bits are shown in Register 6-2.

6.14 Register Definitions: Power Control

REGISTER 6-2: PCON: POWER CONTROL REGISTER

R/W/HS-0/q	R/W/HS-0/q	U-0	R/W/HC-1/q	R/W/HC-1/q	R/W/HC-1/q	R/W/HC-q/u	R/W/HC-q/u
STKOVF	STKUNF	—	$\overline{RWDT}$	$\overline{RMCLR}$	$\overline{RI}$	$\overline{POR}$	$\overline{BOR}$
bit 7							bit 0

Legend:		
HC = Bit is cleared by hardware		HS = Bit is set by hardware
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	q = Value depends on condition

bit 7 **STKOVF:** Stack Overflow Flag bit
1 = A Stack Overflow occurred
0 = A Stack Overflow has not occurred or cleared by firmware

bit 6 **STKUNF:** Stack Underflow Flag bit
1 = A Stack Underflow occurred
0 = A Stack Underflow has not occurred or cleared by firmware

bit 5 **Unimplemented:** Read as ‘0’

bit 4 **$\overline{RWDT}$:** Watchdog Timer Reset Flag bit
1 = A Watchdog Timer Reset has not occurred or set by firmware
0 = A Watchdog Timer Reset has occurred (cleared by hardware)

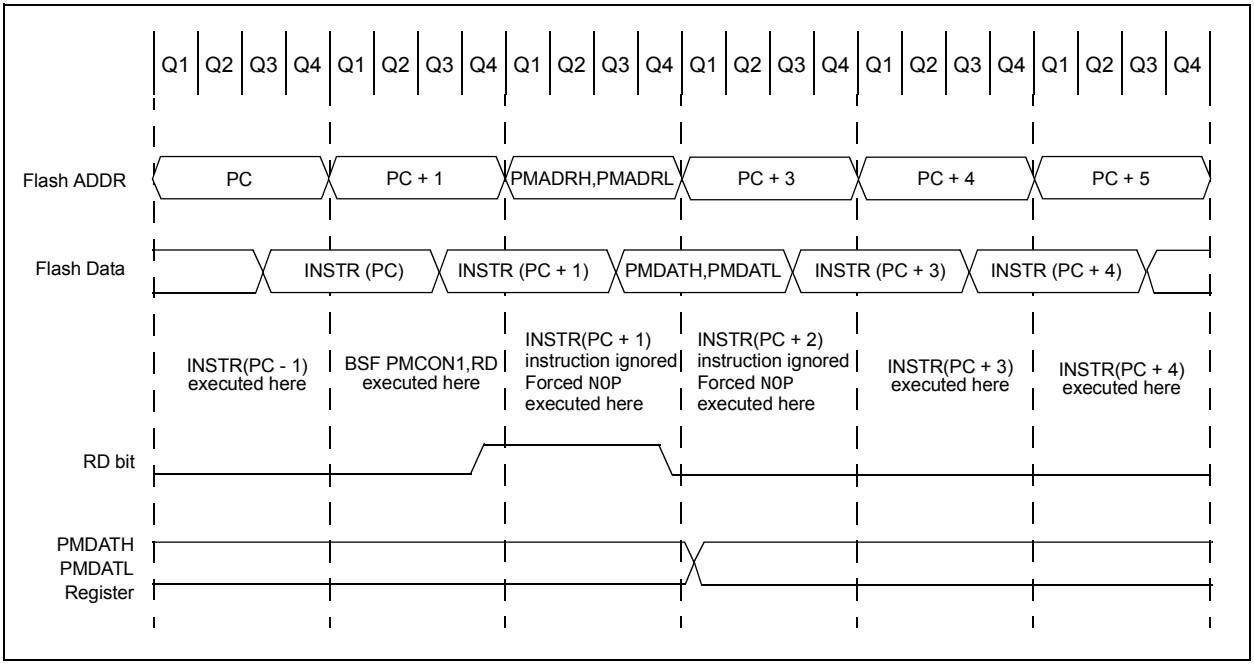
bit 3 **$\overline{RMCLR}$:** $\overline{MCLR}$ Reset Flag bit
1 = A $\overline{MCLR}$ Reset has not occurred or set by firmware
0 = A $\overline{MCLR}$ Reset has occurred (cleared by hardware)

bit 2 **$\overline{RI}$:** RESET Instruction Flag bit
1 = A RESET instruction has not been executed or set by firmware
0 = A RESET instruction has been executed (cleared by hardware)

bit 1 **$\overline{POR}$:** Power-On Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **$\overline{BOR}$:** Brown-Out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Power-on Reset or Brown-out Reset occurs)

FIGURE 10-2: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



EXAMPLE 10-1: FLASH PROGRAM MEMORY READ

```
* This code block will read 1 word of program
* memory at the memory address:
    PROG_ADDR_HI : PROG_ADDR_LO
*   data will be returned in the variables;
*   PROG_DATA_HI, PROG_DATA_LO

    BANKSEL  PMADRL           ; Select Bank for PMCON registers
    MOVLW    PROG_ADDR_LO     ;
    MOVWF    PMADRL           ; Store LSB of address
    MOVLW    PROG_ADDR_HI     ;
    MOVWF    PMADRH           ; Store MSB of address

    BCF      PMCON1,CFGS      ; Do not select Configuration Space
    BSF      PMCON1,RD        ; Initiate read
    NOP                       ; Ignored (Figure 10-2)
    NOP                       ; Ignored (Figure 10-2)

    MOVF     PMDATL,W         ; Get LSB of word
    MOVWF    PROG_DATA_LO     ; Store in user location
    MOVF     PMDATH,W         ; Get MSB of word
    MOVWF    PROG_DATA_HI     ; Store in user location
```

13.0 INTERRUPT-ON-CHANGE

The PORTA, PORTB[(1)] AND PORTC pins can be configured to operate as Interrupt-On-Change (IOC) pins. An interrupt can be generated by detecting a signal that has either a rising edge or a falling edge. Any individual port pin, or combination of port pins, can be configured to generate an interrupt. The interrupt-on-change module has the following features:

- Interrupt-on-Change enable (Master Switch)
- Individual pin configuration
- Rising and falling edge detection
- Individual pin interrupt flags

Figure 13-1 is a block diagram of the IOC module.

Note 1: PORTB available on PIC16(L)F1578/9 only.

13.1 Enabling the Module

To allow individual port pins to generate an interrupt, the IOCIE bit of the INTCON register must be set. If the IOCIE bit is disabled, the edge detection on the pin will still occur, but an interrupt will not be generated.

13.2 Individual Pin Configuration

For each port pin, a rising edge detector and a falling edge detector are present. To enable a pin to detect a rising edge, the associated bit of the IOCxP register is set. To enable a pin to detect a falling edge, the associated bit of the IOCxN register is set.

A pin can be configured to detect rising and falling edges simultaneously by setting both associated bits of the IOCxP and IOCxN registers, respectively.

13.3 Interrupt Flags

The IOCAFx, IOCBFx and IOCCFx bits located in the IOCAF, IOCBF and IOCCF registers, respectively, are status flags that correspond to the interrupt-on-change pins of the associated port. If an expected edge is detected on an appropriately enabled pin, then the status flag for that pin will be set, and an interrupt will be generated if the IOCIE bit is set. The IOCIF bit of the INTCON register reflects the status of all IOCAFx, IOCBFx and IOCCFx bits.

13.4 Clearing Interrupt Flags

The individual status flags, (IOCAFx, IOCBFx and IOCCFx bits), can be cleared by resetting them to zero. If another edge is detected during this clearing operation, the associated status flag will be set at the end of the sequence, regardless of the value actually being written.

In order to ensure that no detected edge is lost while clearing flags, only AND operations masking out known changed bits should be performed. The following sequence is an example of what should be performed.

EXAMPLE 13-1: CLEARING INTERRUPT FLAGS (PORTA EXAMPLE)

```
MOVLW  0xff
XORWF  IOCAF, W
ANDWF  IOCAF, F
```

13.5 Operation in Sleep

The interrupt-on-change interrupt sequence will wake the device from Sleep mode, if the IOCIE bit is set.

If an edge is detected while in Sleep mode, the IOCxF register will be updated prior to the first instruction executed out of Sleep.

16.1.5 INTERRUPTS

The ADC module allows for the ability to generate an interrupt upon completion of an Analog-to-Digital conversion. The ADC Interrupt Flag is the ADIF bit in the PIR1 register. The ADC Interrupt Enable is the ADIE bit in the PIE1 register. The ADIF bit must be cleared in software.

Note 1:	The ADIF bit is set at the completion of every conversion, regardless of whether or not the ADC interrupt is enabled.
2:	The ADC operates during Sleep only when the FRC oscillator is selected.

This interrupt can be generated while the device is operating or while in Sleep. If the device is in Sleep, the interrupt will wake-up the device. Upon waking from Sleep, the next instruction following the SLEEP instruction is always executed. If the user is attempting to wake-up from Sleep and resume in-line code execution, the ADIE bit of the PIE1 register and the PEIE bit of the INTCON register must both be set and the GIE bit of the INTCON register must be cleared. If all three of these bits are set, the execution will switch to the Interrupt Service Routine.

16.1.6 RESULT FORMATTING

The 10-bit ADC conversion result can be supplied in two formats, left justified or right justified. The ADFM bit of the ADCON1 register controls the output format.

Figure 16-3 shows the two output formats.

FIGURE 16-3: 10-BIT ADC CONVERSION RESULT FORMAT

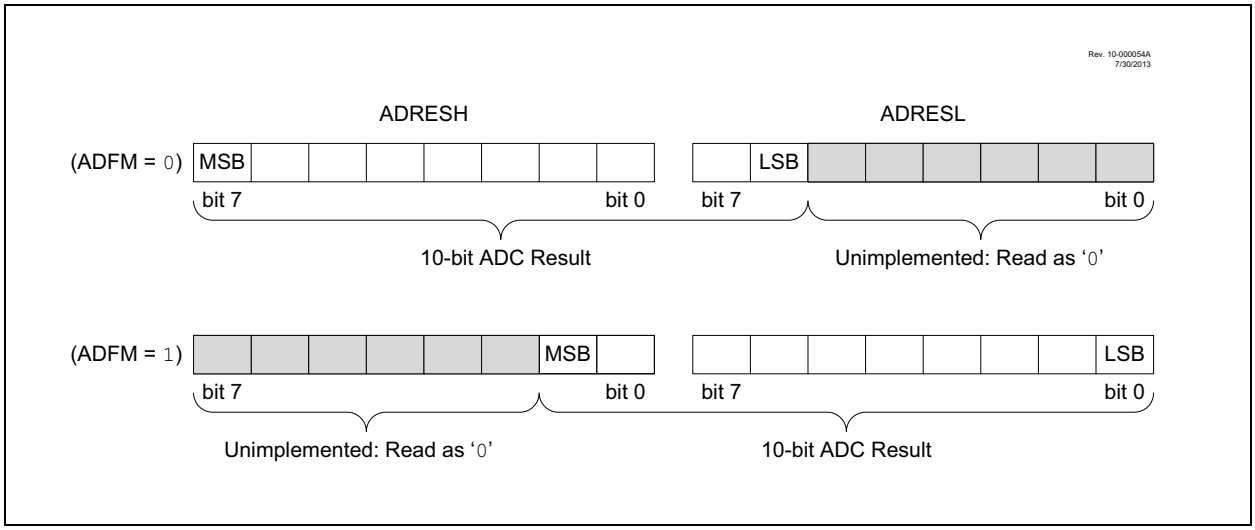


TABLE 22-3: BAUD RATE FORMULAS

Configuration Bits			BRG/EUSART Mode	Baud Rate Formula
SYNC	BRG16	BRGH		
0	0	0	8-bit/Asynchronous	FOSC/[64 (n+1)]
0	0	1	8-bit/Asynchronous	FOSC/[16 (n+1)]
0	1	0	16-bit/Asynchronous	
0	1	1	16-bit/Asynchronous	FOSC/[4 (n+1)]
1	0	x	8-bit/Synchronous	
1	1	x	16-bit/Synchronous	

Legend: x = Don't care, n = value of SPBRGH, SPBRGL register pair.

TABLE 22-4: SUMMARY OF REGISTERS ASSOCIATED WITH THE BAUD RATE GENERATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
BAUDCON	ABDOVF	RCIDL	—	SCKP	BRG16	—	WUE	ABDEN	204
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	203
SPBRGL	BRG<7:0>								205*
SPBRGH	BRG<15:8>								205*
TXSTA	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D	202

Legend: — = unimplemented location, read as '0'. Shaded cells are not used for the Baud Rate Generator.

* Page provides register information.

TABLE 22-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	300	0.16	207
1200	—	—	—	1202	0.16	207	1200	0.00	191	1202	0.16	51
2400	2404	0.16	207	2404	0.16	103	2400	0.00	95	2404	0.16	25
9600	9615	0.16	51	9615	0.16	25	9600	0.00	23	—	—	—
10417	10417	0.00	47	10417	0.00	23	10473	0.53	21	10417	0.00	5
19.2k	19231	0.16	25	19.23k	0.16	12	19.2k	0.00	11	—	—	—
57.6k	55556	-3.55	8	—	—	—	57.60k	0.00	3	—	—	—
115.2k	—	—	—	—	—	—	115.2k	0.00	1	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 1											
	Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 16.000 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	-0.01	4166	300.0	0.00	3839	300.03	0.01	3332	300.0	0.00	2303
1200	1200	-0.03	1041	1200	0.00	959	1200.5	0.04	832	1200	0.00	575
2400	2399	-0.03	520	2400	0.00	479	2398	-0.08	416	2400	0.00	287
9600	9615	0.16	129	9600	0.00	119	9615	0.16	103	9600	0.00	71
10417	10417	0.00	119	10378	-0.37	110	10417	0.00	95	10473	0.53	65
19.2k	19.23k	0.16	64	19.20k	0.00	59	19.23k	0.16	51	19.20k	0.00	35
57.6k	56.818	-1.36	21	57.60k	0.00	19	58.82k	2.12	16	57.60k	0.00	11
115.2k	113.636	-1.36	10	115.2k	0.00	9	111.11k	-3.55	8	115.2k	0.00	5

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 1											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	299.9	-0.02	1666	300.1	0.04	832	300.0	0.00	767	300.5	0.16	207
1200	1199	-0.08	416	1202	0.16	207	1200	0.00	191	1202	0.16	51
2400	2404	0.16	207	2404	0.16	103	2400	0.00	95	2404	0.16	25
9600	9615	0.16	51	9615	0.16	25	9600	0.00	23	—	—	—
10417	10417	0.00	47	10417	0.00	23	10473	0.53	21	10417	0.00	5
19.2k	19.23k	0.16	25	19.23k	0.16	12	19.20k	0.00	11	—	—	—
57.6k	55556	-3.55	8	—	—	—	57.60k	0.00	3	—	—	—
115.2k	—	—	—	—	—	—	115.2k	0.00	1	—	—	—

TABLE 22-5: BAUD RATES FOR ASYNCHRONOUS MODES (CONTINUED)

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 16.000 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	16665	300.0	0.00	15359	300.0	0.00	13332	300.0	0.00	9215
1200	1200	-0.01	4166	1200	0.00	3839	1200.1	0.01	3332	1200	0.00	2303
2400	2400	0.02	2082	2400	0.00	1919	2399.5	-0.02	1666	2400	0.00	1151
9600	9597	-0.03	520	9600	0.00	479	9592	-0.08	416	9600	0.00	287
10417	10417	0.00	479	10425	0.08	441	10417	0.00	383	10433	0.16	264
19.2k	19.23k	0.16	259	19.20k	0.00	239	19.23k	0.16	207	19.20k	0.00	143
57.6k	57.47k	-0.22	86	57.60k	0.00	79	57.97k	0.64	68	57.60k	0.00	47
115.2k	116.3k	0.94	42	115.2k	0.00	39	114.29k	-0.79	34	115.2k	0.00	23

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 1 or SYNC = 1, BRG16 = 1											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	300.0	0.00	6666	300.0	0.01	3332	300.0	0.00	3071	300.1	0.04	832
1200	1200	-0.02	1666	1200	0.04	832	1200	0.00	767	1202	0.16	207
2400	2401	0.04	832	2398	0.08	416	2400	0.00	383	2404	0.16	103
9600	9615	0.16	207	9615	0.16	103	9600	0.00	95	9615	0.16	25
10417	10417	0	191	10417	0.00	95	10473	0.53	87	10417	0.00	23
19.2k	19.23k	0.16	103	19.23k	0.16	51	19.20k	0.00	47	19.23k	0.16	12
57.6k	57.14k	-0.79	34	58.82k	2.12	16	57.60k	0.00	15	—	—	—
115.2k	117.6k	2.12	16	111.1k	-3.55	8	115.2k	0.00	7	—	—	—

FIGURE 23-4: STANDARD PWM MODE TIMING DIAGRAM

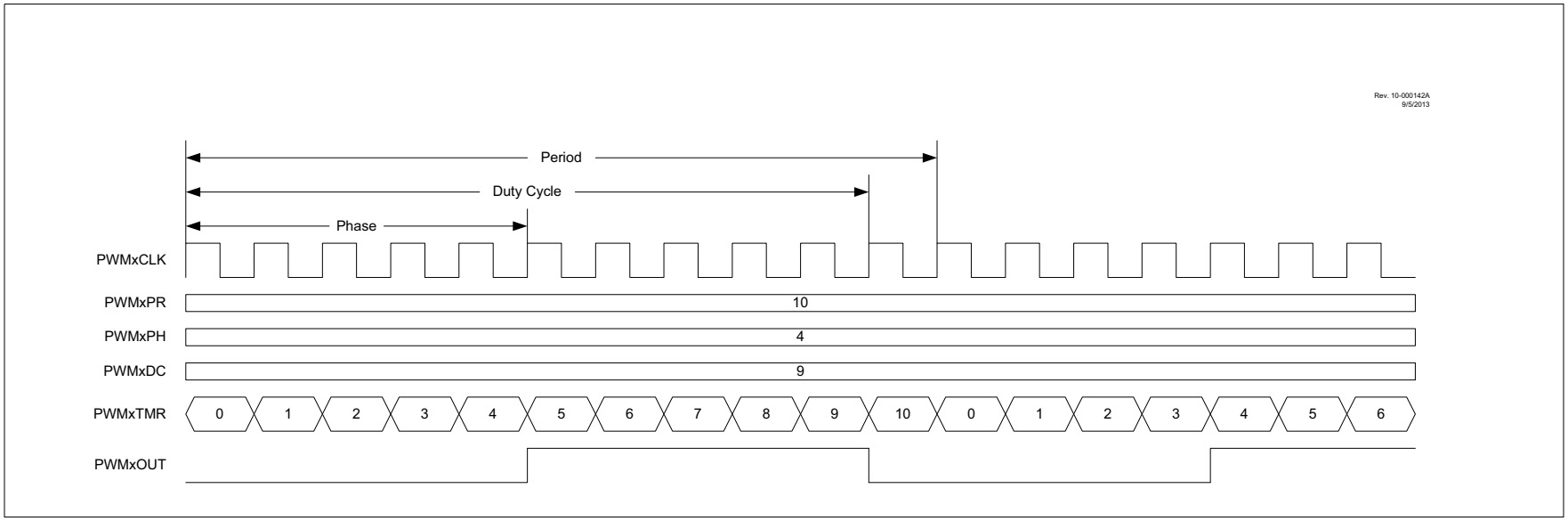
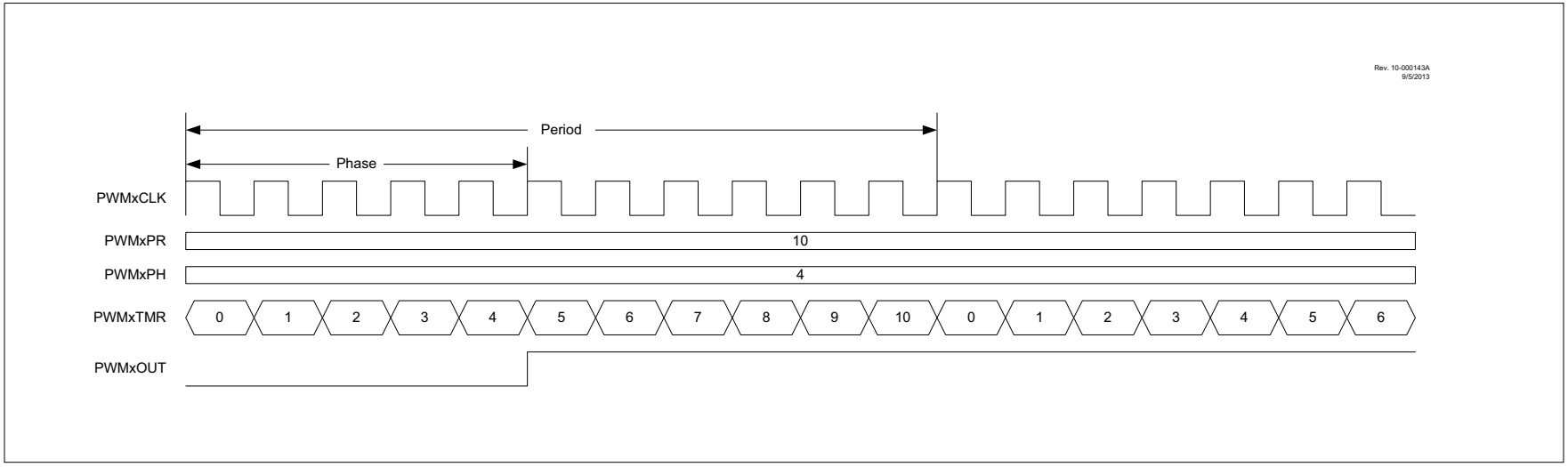


FIGURE 23-5: SET ON MATCH PWM MODE TIMING DIAGRAM



REGISTER 23-4: PWMxCLKCON: PWM CLOCK CONTROL REGISTER

U-0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	R/W-0/0	R/W-0/0
—	PS<2:0>			—	—	CS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '0'

bit 6-4 **PS<2:0>:** Clock Source Prescaler Select bits
111 = Divide clock source by 128
110 = Divide clock source by 64
101 = Divide clock source by 32
100 = Divide clock source by 16
011 = Divide clock source by 8
010 = Divide clock source by 4
001 = Divide clock source by 2
000 = No Prescaler

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CS<1:0>:** Clock Source Select bits
11 = Reserved
10 = LFINTOSC (continues to operate during Sleep)
01 = HFINTOSC (continues to operate during Sleep)
00 = FOSC

TABLE 27-11: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
30	TMCL	$\overline{MCLR}$ Pulse Width (low)	2	—	—	µs	
31	TWDTLP	Low-Power Watchdog Timer Time-out Period	10	16	27	ms	VDD = 3.3V-5V, 1:512 Prescaler used
32	TOST	Oscillator Start-up Timer Period(1)	—	1024	—	TOSC	
33*	TPWRT	Power-up Timer Period	40	65	140	ms	$\overline{PWRTE}$ = 0
34*	TIOZ	I/O high-impedance from $\overline{MCLR}$ Low or Watchdog Timer Reset	—	—	2.0	µs	
35	VBOR	Brown-out Reset Voltage(2)	2.55 2.35 1.80	2.70 2.45 1.90	2.85 2.58 2.05	V V V	BORV = 0 BORV = 1 (PIC16F1574/5/8/9) BORV = 1 (PIC16LF1574/5/8/9)
36*	VHYST	Brown-out Reset Hysteresis	0	25	60	mV	-40°C ≤ TA ≤ +85°C
37*	TBORDC	Brown-out Reset DC Response Time	1	16	35	µs	VDD ≤ VBOR
38	VLPBOR	Low-Power Brown-Out Reset Voltage	1.8	2.1	2.5	V	LPBOR = 1

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: By design, the Oscillator Start-up Timer (OST) counts the first 1024 cycles, independent of frequency.

2: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

FIGURE 27-9: BROWN-OUT RESET TIMING AND CHARACTERISTICS

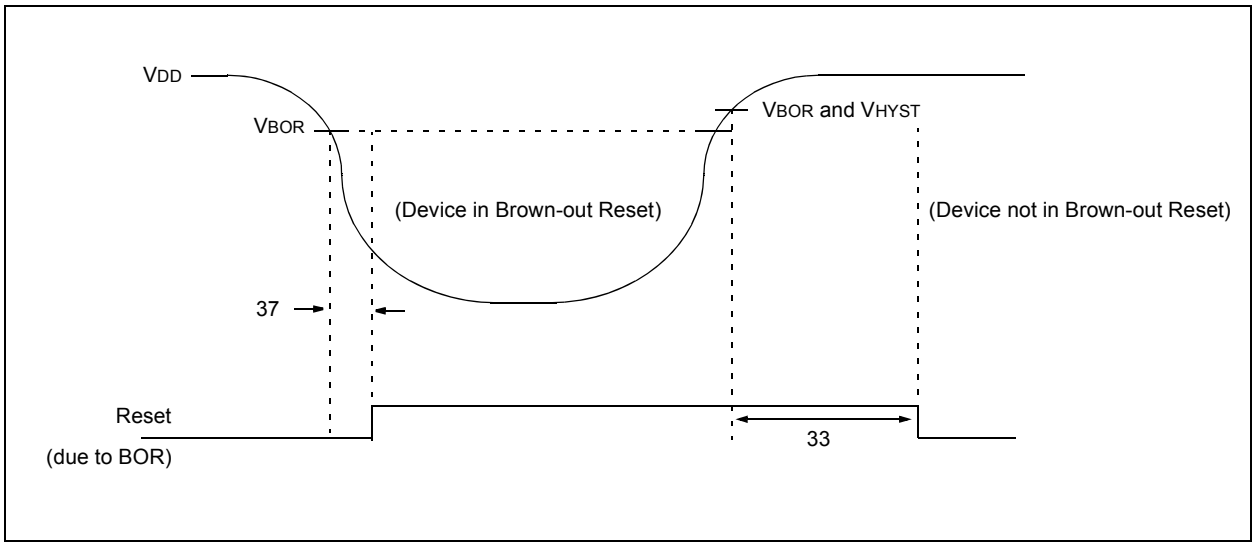


TABLE 27-13: ANALOG-TO-DIGITAL CONVERTER (ADC) CHARACTERISTICS(1,2,3)

Operating Conditions (unless otherwise stated) VDD = 3.0V, TA = 25°C							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
AD01	NR	Resolution	—	—	10	bit	
AD02	EIL	Integral Error	—	±1	±1.7	LSb	VREF = 3.0V
AD03	EDL	Differential Error	—	±1	±1	LSb	No missing codes VREF = 3.0V
AD04	EOFF	Offset Error	—	±1	±2.5	LSb	VREF = 3.0V
AD05	EGN	Gain Error	—	±1	±2.0	LSb	VREF = 3.0V
AD06	VREF	Reference Voltage	1.8	—	VDD	V	VREF = (VRPOS - VRNEG) (**Note 4**)
AD07	VAIN	Full-Scale Range	VSS	—	VREF	V	
AD08	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	10	kΩ	Can go higher if external 0.01μF capacitor is present on input pin.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

2: The ADC conversion result never decreases with an increase in the input voltage and has no missing codes.

3: See **Section 28.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.

4: ADC VREF is selected by ADPREF<0> bit.

TABLE 27-15: COMPARATOR SPECIFICATIONS(1)

Operating Conditions (unless otherwise stated) VDD = 3.0V, TA = 25°C							
Param. No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
CM01	VIOFF	Input Offset Voltage	—	±7.5	±60	mV	CxSP = 1, VICM = VDD/2
CM02	VICM	Input Common Mode Voltage	0	—	VDD	V	
CM03	CMRR	Common Mode Rejection Ration	—	50	—	dB	
CM04A	TRESP(2)	Response Time Rising Edge	—	400	800	ns	CxSP = 1
CM04B		Response Time Falling Edge	—	200	400	ns	CxSP = 1
CM04C		Response Time Rising Edge	—	1200	—	ns	CxSP = 0
CM04D		Response Time Falling Edge	—	550	—	ns	CxSP = 0
CM05*	TMC2OV	Comparator Mode Change to Output Valid	—	—	10	µs	
CM06	CHYSTER	Comparator Hysteresis	—	25	—	mV	CxHYS = 1, CxSP = 1

* These parameters are characterized but not tested.

Note 1: See **Section 28.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.

2: Response time measured with one comparator input at VDD/2, while the other input transitions from VSS to VDD.

TABLE 27-16: DIGITAL-TO-ANALOG CONVERTER (DAC) SPECIFICATIONS(1)

Operating Conditions (unless otherwise stated) VDD = 3.0V, TA = 25°C							
Param. No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
DAC01*	CLSB	Step Size	—	VDD/32	—	V	
DAC02*	CACC	Absolute Accuracy	—	—	± 1/2	LSb	
DAC03*	CR	Unit Resistor Value (R)	—	5K	—	Ω	
DAC04*	CST	Settling Time(2)	—	—	10	µs	

* These parameters are characterized but not tested.

Note 1: See **Section 28.0 "DC and AC Characteristics Graphs and Charts"** for operating characterization.

2: Settling time measured while DACR<4:0> transitions from '0000' to '1111'.

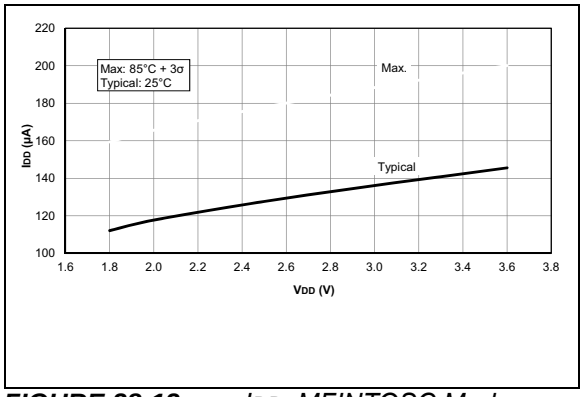


FIGURE 28-13: *IDD, MFINTOSC Mode, FOSC = 500 kHz, PIC16LF1574/5/8/9 Only.*

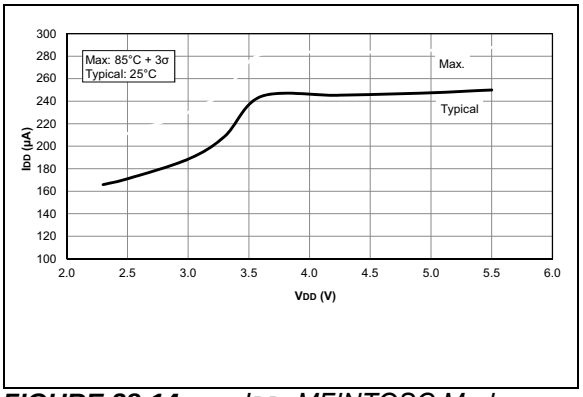


FIGURE 28-14: *IDD, MFINTOSC Mode, FOSC = 500 kHz, PIC16F1574/5/8/9 Only.*

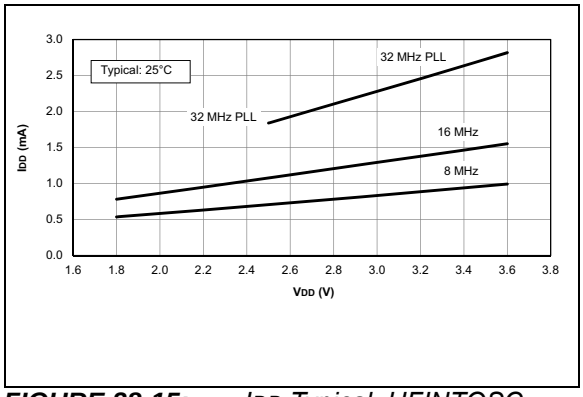


FIGURE 28-15: *IDD Typical, HFINTOSC Mode, PIC16LF1574/5/8/9 Only.*

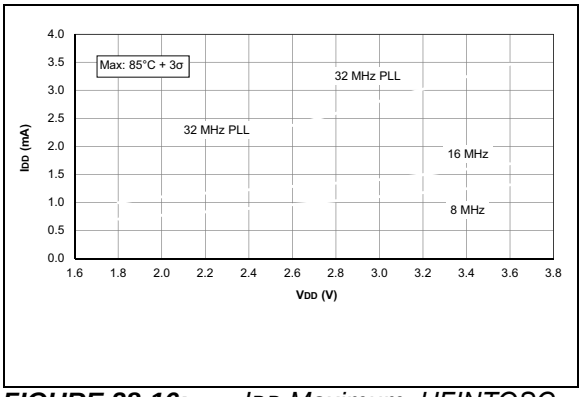


FIGURE 28-16: *IDD Maximum, HFINTOSC Mode, PIC16LF1574/5/8/9 Only.*

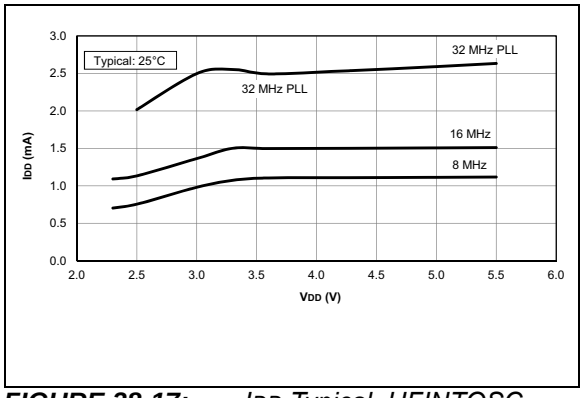


FIGURE 28-17: *IDD Typical, HFINTOSC Mode, PIC16F1574/5/8/9 Only.*

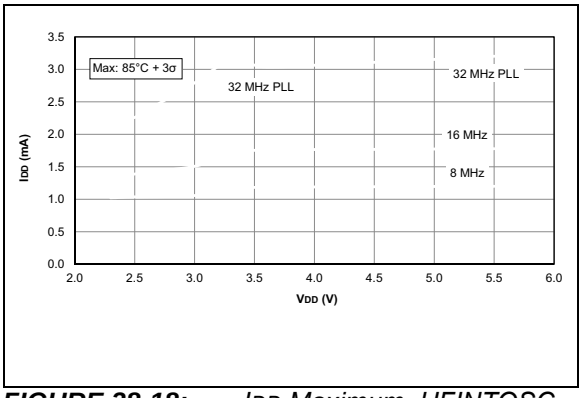


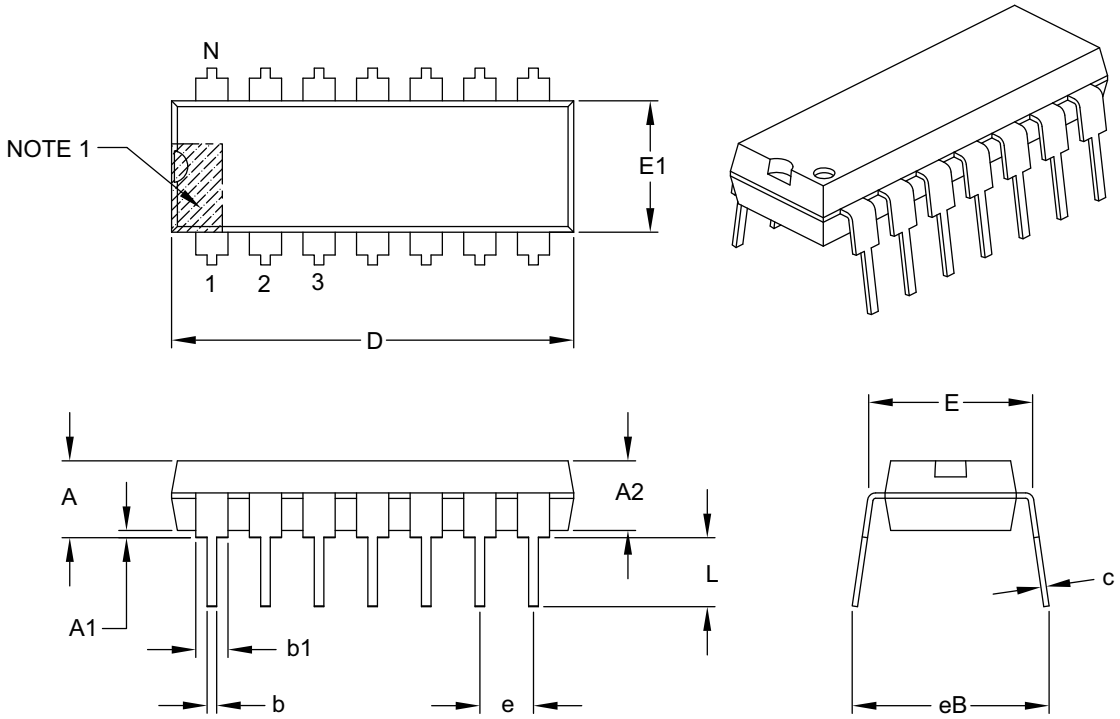
FIGURE 28-18: *IDD Maximum, HFINTOSC Mode, PIC16F1574/5/8/9 Only.*

30.2 Package Details

The following sections give the technical details of the packages.

14-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.290	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.735	.750	.775
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.015
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

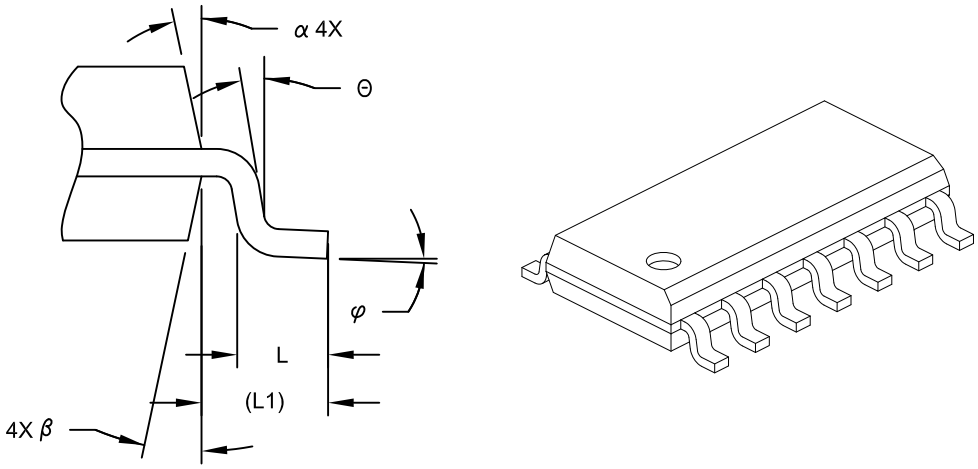
1. Pin 1 visual index feature may vary, but must be located with the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-005B

14-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		14	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		8.65 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.10	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

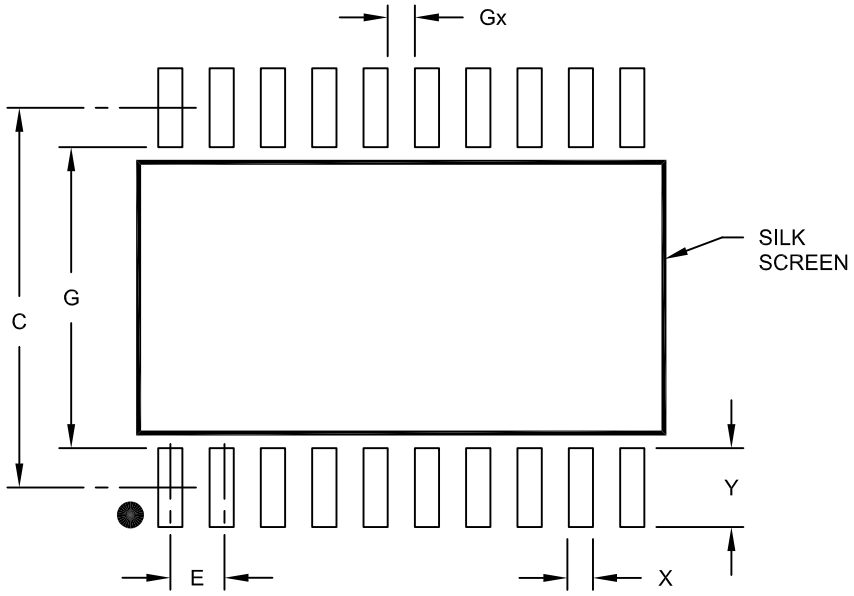
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-065C Sheet 2 of 2

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width (X20)	X			0.60
Contact Pad Length (X20)	Y			1.95
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.45		

Notes:

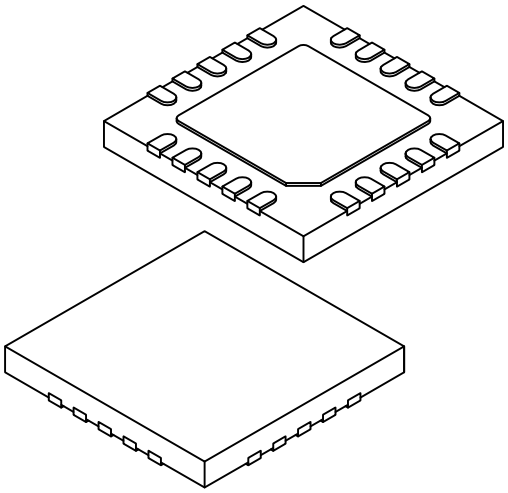
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2094A

20-Lead Ultra Thin Plastic Quad Flat, No Lead Package (GZ) - 4x4x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N		20	
Pitch	e		0.50 BSC	
Overall Height	A	0.45	0.50	0.55
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.127 REF	
Overall Width	E		4.00 BSC	
Exposed Pad Width	E2	2.60	2.70	2.80
Overall Length	D		4.00 BSC	
Exposed Pad Length	D2	2.60	2.70	2.80
Terminal Width	b	0.20	0.25	0.30
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-255A Sheet 2 of 2